

12 said inner and outer [sides] edges being uniformly spaced apart defining
13 therebetween a chip-support zone for the frame having defined dimensions.
14

15 said [zone being] outer edges of the sidebars being recessed from the outer edges of
16 the chip such that the frame is smaller a corresponding dimension of the chip, so as to avoid
17 formation of a fillet of chip attach material proximate to the outer edges of the chip when the chip is
18 attached to the frame, [each sidebar having an upper chip-supporting surface for engaging the bottom
19 surface of the chip].
20

21 Cancel ~~claim 9~~ without prejudice.
22

23 16. (New) A lead frame, for an integrated circuit chip having a frame engaging
24 bottom surface for attachment to the frame by means of a chip attach material, said chip being
25 formed with outer edges having defined dimensions, said frame comprising:
26

27 a unitary apertured frame having a chip-supporting surface for engaging the bottom
28 of the surface of the chip with the chip attach material therebetween, said frame having an outer
29 edge, and an aperture formed with an inner edge defining the through central aperture,
30

31 said inner and outer edges being uniformly spaced apart defining therebetween a
32 chip-support zone having defined dimensions,
33

34 said outer edge of the apertured frame being recessed from the outer edges of the
35 chip such that the frame is smaller than a corresponding dimension of the chip, so as to avoid
36 formation of a fillet of chip attach material to the outer edges of the chip when the chip is attached to
37 the apertured frame.
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39
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